

Amendments to the Claims:

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1- 17 (Previously Canceled).

Claims 18 – 21 (Cancelled).

Please add the following new claims:

22. (new) A method of making a circuitized substrate assembly, said method comprising:

providing a first circuitized substrate including alternating layers of dielectric material and conductive material therein and further including an opening therein extending substantially through the thickness of said first circuitized substrate;

providing a layer of dielectric material on an external surface of said first circuitized substrate;

providing a second circuitized substrate including alternating layers of dielectric material and conductive material therein and an opening therein extending substantially through the thickness of said second circuitized substrate;

substantially completely filling said opening in said second circuitized substrate with a quantity of electrically conductive paste, said opening within said first dielectric substrate not including any of said conductive paste therein;

aligning said first and second circuitized substrates such that said opening in said second circuitized substrate having said electrically conductive paste therein aligns with said opening in said first circuitized substrate not having said conductive paste therein, said conductive paste not being engaged by a dielectric layer; and

thereafter bonding said first and second circuitized substrates together such that said electrically conductive paste only partly fills said opening in said first circuitized substrate while also substantially filling said opening in said second circuitized substrate, said layer of dielectric material on said external surface of said first circuitized substrate extending within said opening of said first circuitized substrate.

23. (new) The method of claim 22 wherein said bonding of said first and second circuitized substrates is achieved by laminating.

24. (new) The method of claim 23 wherein said laminating is accomplished at a temperature of from about 70 to about 200 degrees Celsius.

25. (new) The method of claim 24 wherein said laminating is accomplished at a pressure of from about 50 to about 500 pounds per square inch.

26. (new) The method of claim 25 wherein said laminating is accomplished for a time period of from about 30 to about 180 minutes.